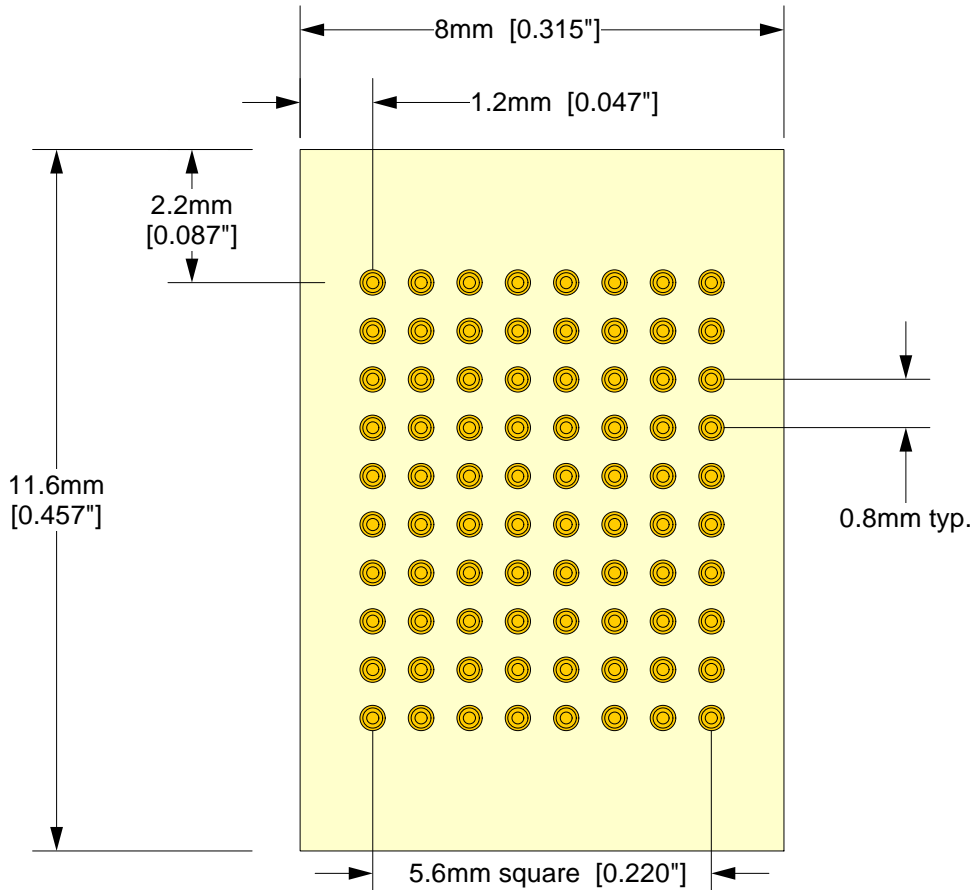
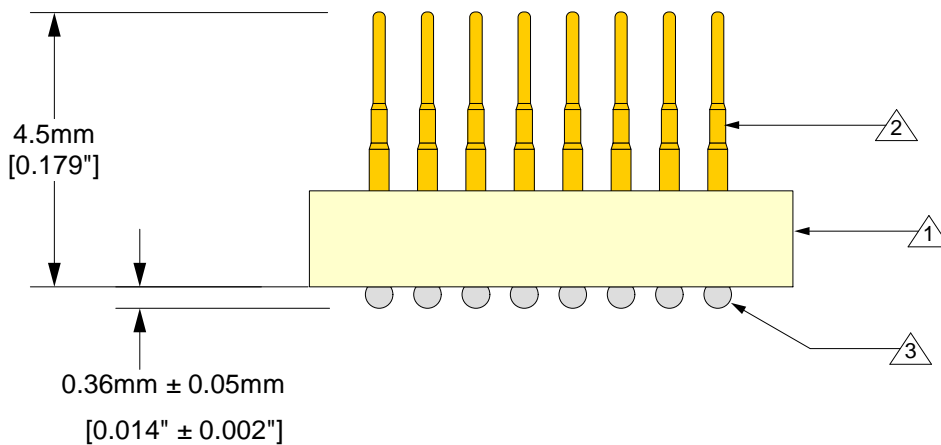


Top View



Side View



- 1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"]
FR4/G10 or equivalent high temp material;
Non-clad
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish-
0.25 μ m [10 μ] Au over 1.27 μ m [50 μ] Ni (min.).
- 3 Solder Balls: Sn96.5Ag3.0Cu0.5

RoHS COMPLIANT

Description: Giga-snaP BGA SMT Foot
80 position terminal pins (0.8mm centers, 8x10 array) to SMT solder balls (BGA type). Pin assignment 1:1.

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SF-BGA80L-B-61F Drawing	Status: Released	Scale: 8:1	Rev: B
<p>© 2009 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Drawing: A. Evans		Date: 06/01/09
	File: SF-BGA80L-B-61F Dwg.mcd		Modified: 08/28/14